

Silicon N Channel MOS Type (U-MOSII)/Silicon Epitaxial Schottky Barrier Diode

## SSM5H01TU

### DC-DC Converter

- Combined Nch MOSFET and Schottky Diode into one Package.
- Low RDS (ON) and Low VF

### Absolute Maximum Ratings (Ta = 25°C) MOSFET

Characteristics	Symbol	Rating	Unit
Drain-Source voltage	V <sub>DS</sub>	30	V
Gate-Source voltage	V <sub>GSS</sub>	±20	V
Drain current	DC	I <sub>D</sub>	A
	Pulse	I <sub>DP</sub> (Note 2)	
Drain power dissipation	P <sub>D</sub> (Note 1)	0.5	W
	t = 10s	0.8	
Channel temperature	T <sub>ch</sub>	150	°C

### Absolute Maximum Ratings (Ta = 25°C) SCHOTTKY DIODE

Characteristics	Symbol	Rating	Unit
Maximum (peak) reverse voltage	V <sub>RM</sub>	25	V
Reverse voltage	V <sub>R</sub>	20	V
Average forward current	I <sub>O</sub>	0.5	A
Peak one cycle surge forward current (non-repetitive)	I <sub>FSM</sub>	2 (50 Hz)	A
Junction temperature	T <sub>j</sub>	125	°C

### Absolute Maximum Ratings (Ta = 25°C) MOSFET, DIODE COMMON

Characteristics	Symbol	Rating	Unit
Storage temperature	T <sub>stg</sub>	–55~125	°C
Operating temperature	T <sub>opr</sub> (Note 3)	–40~100	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

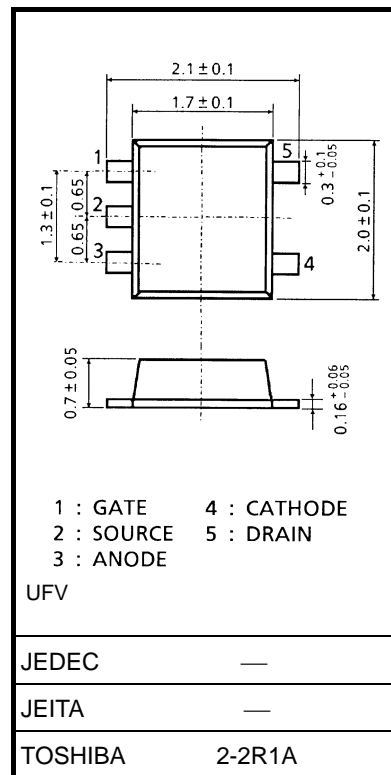
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on FR4 board  
(25.4 mm × 25.4 mm × 1.6 t, Cu pad: 645 mm<sup>2</sup>)

Note 2: The pulse width limited by max channel temperature.

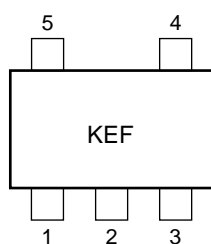
Note 3: Operating temperature limited by max channel temperature and max junction temperature.

Unit: mm

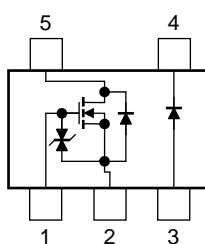


Weight: 7 mg (typ.)

## Marking



## Equivalent Circuit



## Handling Precaution

When handling individual devices (which are not yet mounting on a circuit board), be sure that the environment is protected against electrostatic discharge. Operators should wear anti-static clothing and use containers and other objects that are made of anti-static materials.

The Channel-to-Ambient thermal resistance  $R_{th(ch-a)}$  and the drain power dissipation  $P_D$  vary according to the board material, board area, board thickness and pad area. When using this device, please take heat dissipation fully into account.

## MOSFET

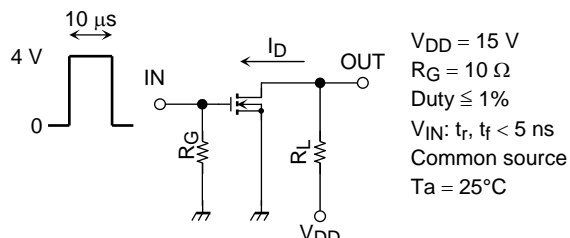
### Electrical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	$I_{GSS}$	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$	—	—	$\pm 1$	$\mu\text{A}$
Drain-Source breakdown voltage	$V_{(BR) DSS}$	$I_D = 1 \text{ mA}, V_{GS} = 0$	30	—	—	V
	$V_{(BR) DSX}$	$I_D = 1 \text{ mA}, V_{GS} = -20 \text{ V}$	15	—	—	
Drain Cut-off current	$I_{DSS}$	$V_{DS} = 30 \text{ V}, V_{GS} = 0$	—	—	1	$\mu\text{A}$
Gate threshold voltage	$V_{th}$	$V_{DS} = 5 \text{ V}, I_D = 0.1 \text{ mA}$	1.0	—	2.4	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 5 \text{ V}, I_D = 0.7 \text{ A}$ (Note 4)	0.9	1.8	—	S
Drain-Source ON resistance	$R_{DS(ON)}$	$I_D = 0.7 \text{ A}, V_{GS} = 10 \text{ V}$ (Note 4)	—	140	200	$\text{m}\Omega$
		$I_D = 0.7 \text{ A}, V_{GS} = 4 \text{ V}$ (Note 4)	—	250	450	
Input capacitance	$C_{iss}$	$V_{DS} = 15 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	—	106	—	pF
Reverse transfer capacitance	$C_{rss}$	$V_{DS} = 15 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	—	15	—	pF
Output capacitance	$C_{oss}$	$V_{DS} = 15 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	—	28	—	pF
Switching time	Turn-on time	$t_{on}$	$V_{DD} = 15 \text{ V}, I_D = 0.7 \text{ A}$		18	ns
	Turn-off time	$t_{off}$			10	
		$V_{GS} = 0 \sim 4 \text{ V}, R_G = 10 \Omega$	—	10	—	

Note 4: Pulse measurement

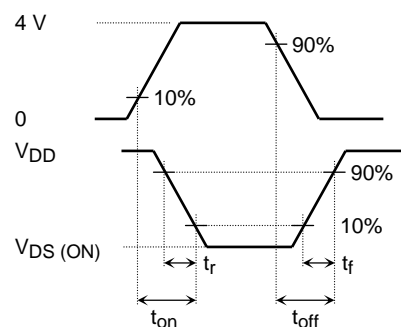
### Switching Time Test Circuit

#### (a) Test circuit



#### (b) $V_{IN}$

#### (c) $V_{OUT}$



### Precaution

$V_{th}$  can be expressed as voltage between gate and source when low operating current value is  $I_D = 100 \mu\text{A}$  for this product. For normal switching operation,  $V_{GS(on)}$  requires higher voltage than  $V_{th}$  and  $V_{GS(off)}$  requires lower voltage than  $V_{th}$ .

(Relationship can be established as follows:  $V_{GS(off)} < V_{th} < V_{GS(on)}$ )

Please take this into consideration for using the device.

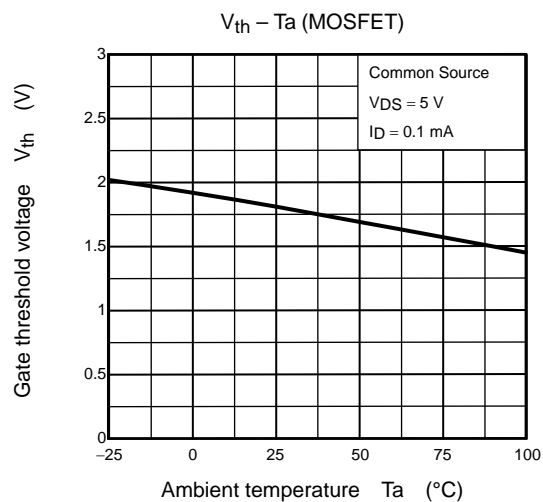
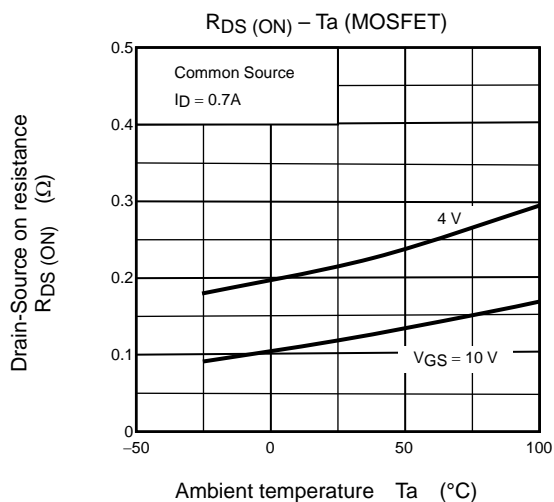
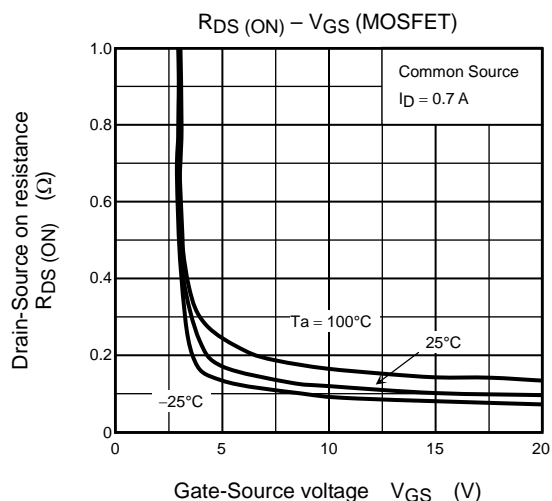
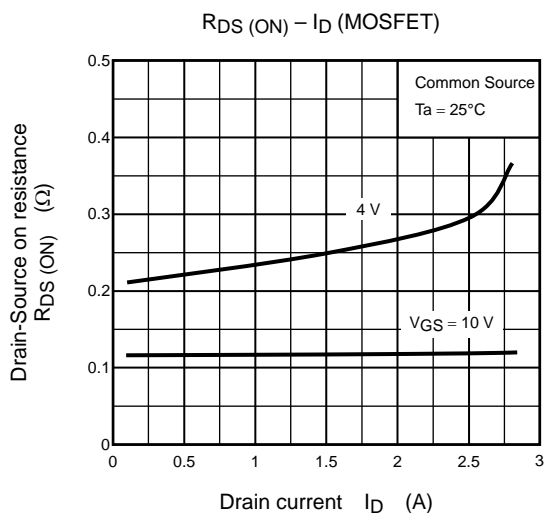
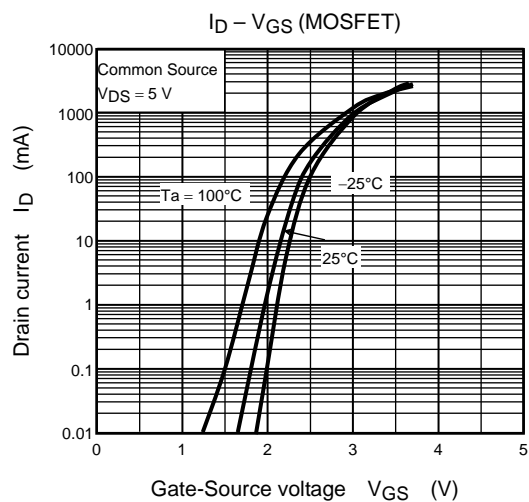
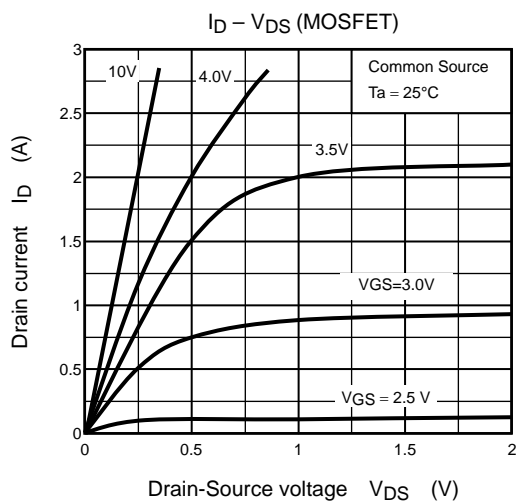
**Schottky Diode****Electrical Characteristics (Ta = 25°C)**

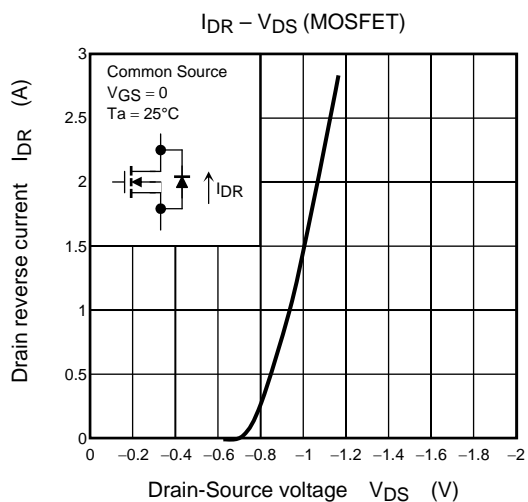
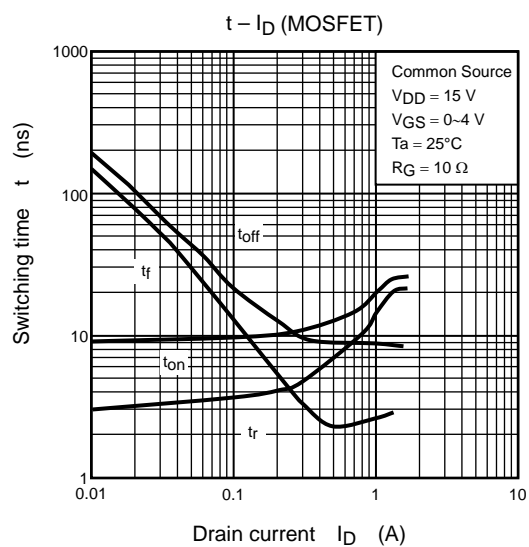
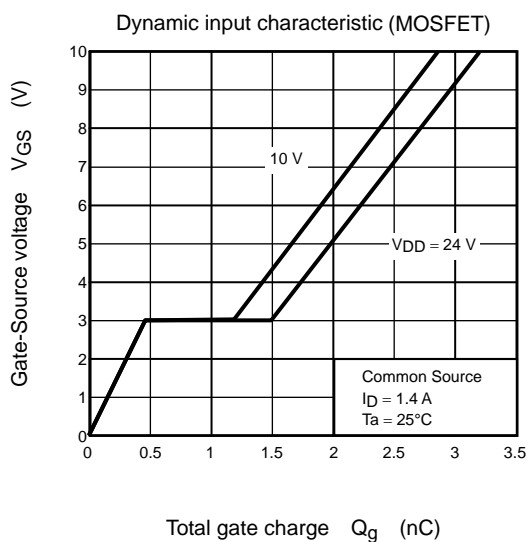
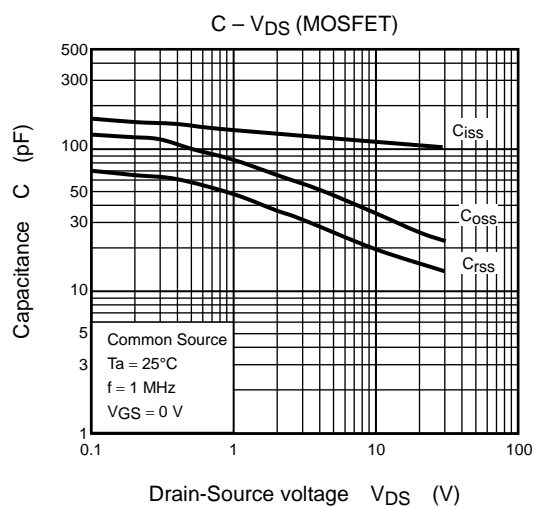
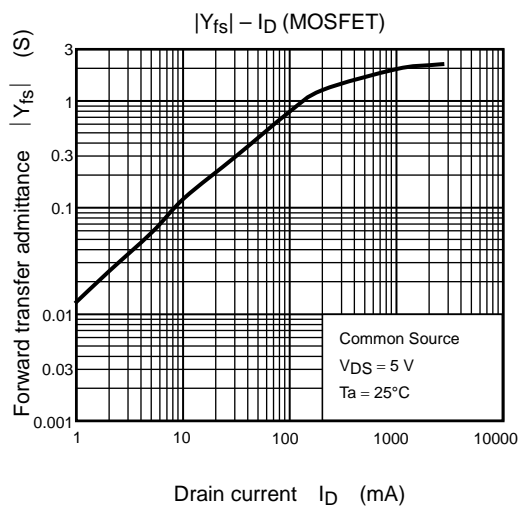
Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Forward voltage	V <sub>F</sub> (1)	I <sub>F</sub> = 0.3 A	—	0.38	0.45	V
	V <sub>F</sub> (2)	I <sub>F</sub> = 0.5 A	—	0.43	—	V
Reverse current	I <sub>R</sub>	V <sub>R</sub> = 20 V	—	—	50	μA
Total capacitance	C <sub>T</sub>	V <sub>R</sub> = 0 V, f = 1 MHz	—	46	—	pF

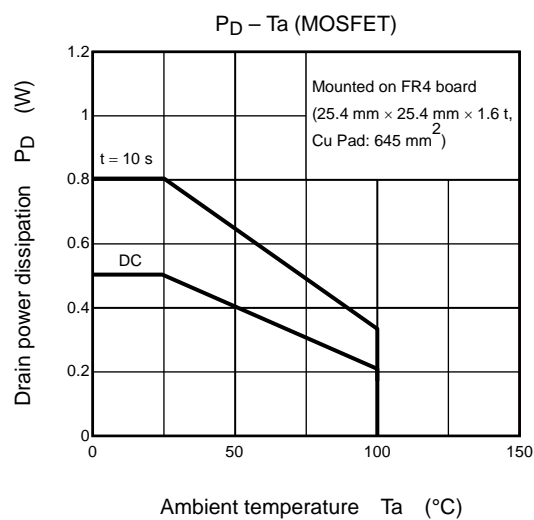
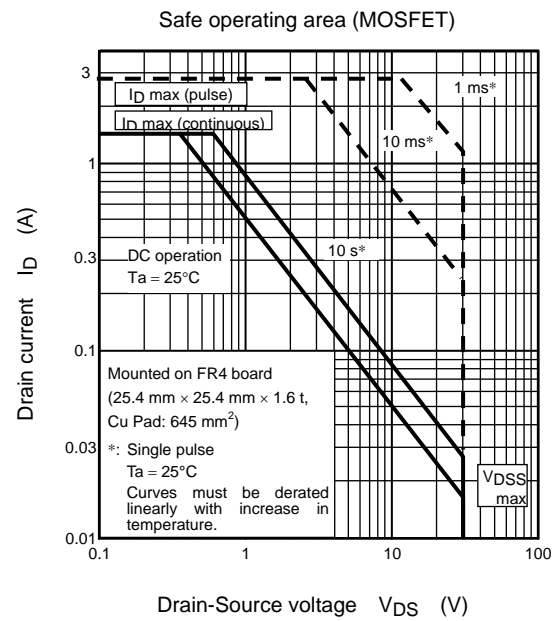
**Precaution**

The schottky barrier diode of this product are having large-reverse-current-leakage characteristic compare to the other switching diodes. This current leakage and not proper operating temperature or voltage may cause thermal runaway. Please take forward and reverse loss into consideration when you design.

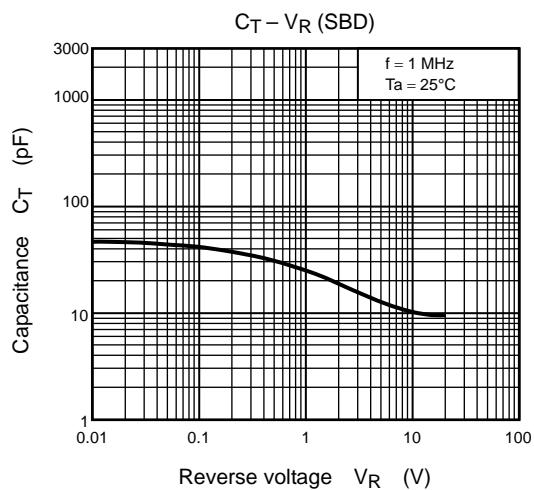
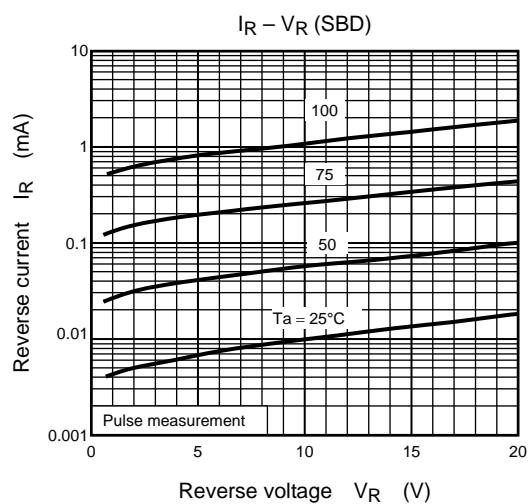
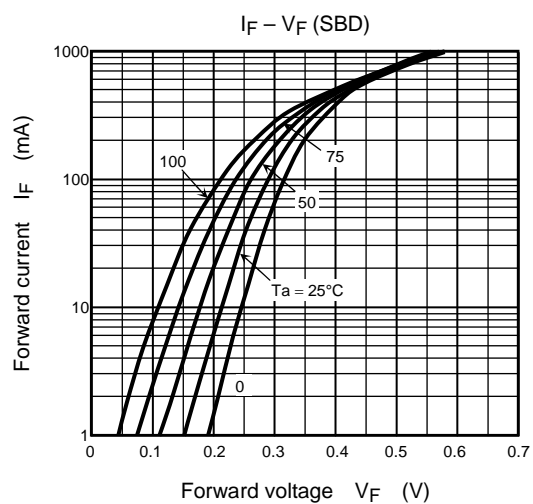
## MOSFET Electrical Characteristics Graph



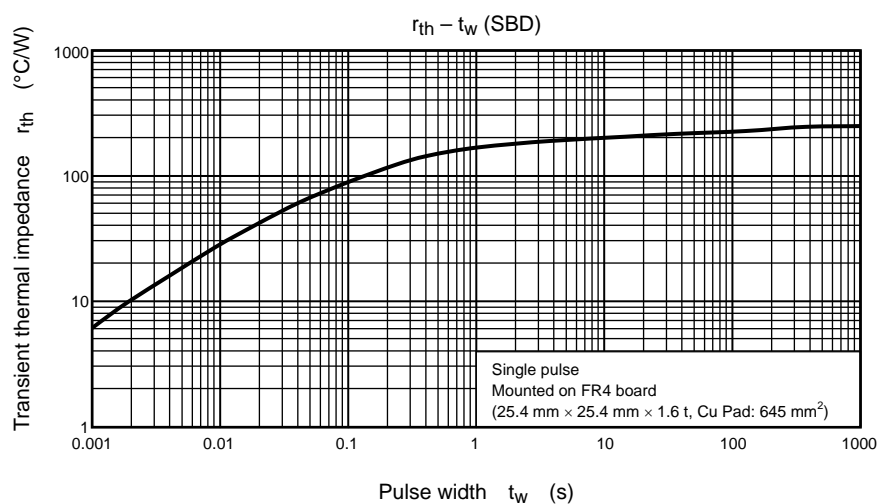
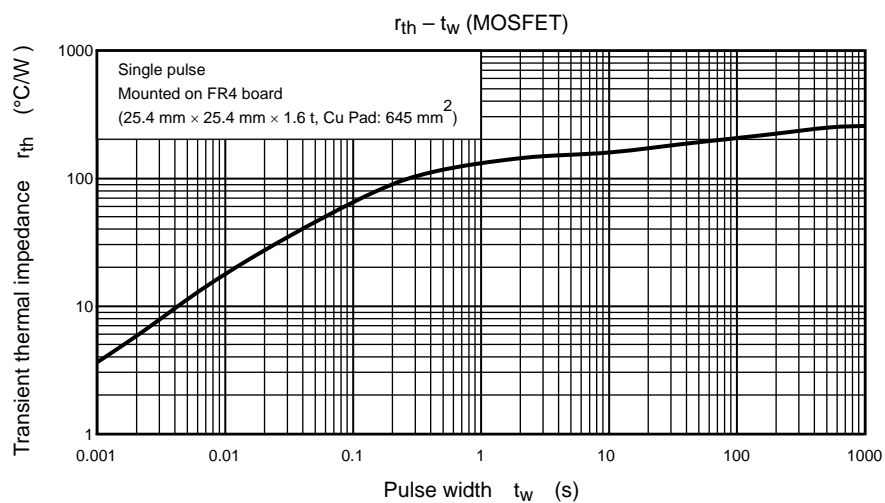




## SBD Electrical Characteristics Graph



## Transient thermal impedance Graph



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